

Title (en)

PHOTOELECTRIC SENSOR AND MANUFACTURING METHOD THEREFOR, AND DISPLAY DEVICE

Title (de)

PHOTOELEKTRISCHER SENSOR UND HERSTELLUNGSVERFAHREN DAFÜR SOWIE ANZEIGEVORRICHTUNG

Title (fr)

CAPTEUR PHOTOÉLECTRIQUE ET SON PROCÉDÉ DE FABRICATION, ET DISPOSITIF D'AFFICHAGE

Publication

EP 3633726 A4 20210526 (EN)

Application

EP 18806654 A 20180517

Priority

- CN 201710383647 A 20170526
- CN 2018087253 W 20180517

Abstract (en)

[origin: US2019198543A1] The application discloses a photoelectric sensor, a fabricating method thereof, and a display device. The method for fabricating the photoelectric sensor, includes: fabricating a thin film transistor (TFT) array and a photodiode array on a silicon substrate; transferring the TFT array onto a base substrate by a micro transfer process; and placing the photodiode array on the base substrate formed with the TFT array, in a manner that an orthographic projection of the photodiode array on the base substrate overlaps with an orthographic projection of the TFT array on the base substrate.

IPC 8 full level

H01L 27/146 (2006.01); **G06F 21/32** (2013.01); **H01L 27/12** (2006.01)

CPC (source: CN EP US)

G06F 21/32 (2013.01 - US); **H01L 27/14612** (2013.01 - CN US); **H01L 27/14621** (2013.01 - US); **H01L 27/14632** (2013.01 - EP); **H01L 27/14636** (2013.01 - US); **H01L 27/14647** (2013.01 - US); **H01L 27/14665** (2013.01 - EP US); **H01L 27/14683** (2013.01 - CN US); **H01L 27/14687** (2013.01 - EP); **G06F 21/32** (2013.01 - EP); **H01L 27/14678** (2013.01 - EP US)

Citation (search report)

- [XY] US 2017005126 A1 20170105 - YAMAZAKI SHUNPEI [JP], et al
- [Y] CN 1536419 A 20041013 - TONGBAO PHOTOELECTRIC CO LTD [CN]
- [Y] US 2002079512 A1 20020627 - YAMAZAKI SHUNPEI [JP], et al
- [XA] WO 2005114749 A1 20051201 - SEMICONDUCTOR ENERGY LAB [JP], et al
- [Y] CN 106709455 A 20170524 - ZHANG YIFAN
- See references of WO 2018214799A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

US 10886310 B2 20210105; **US 2019198543 A1 20190627**; CN 107248518 A 20171013; CN 107248518 B 20200417; EP 3633726 A1 20200408; EP 3633726 A4 20210526; WO 2018214799 A1 20181129

DOCDB simple family (application)

US 201816327892 A 20180517; CN 201710383647 A 20170526; CN 2018087253 W 20180517; EP 18806654 A 20180517